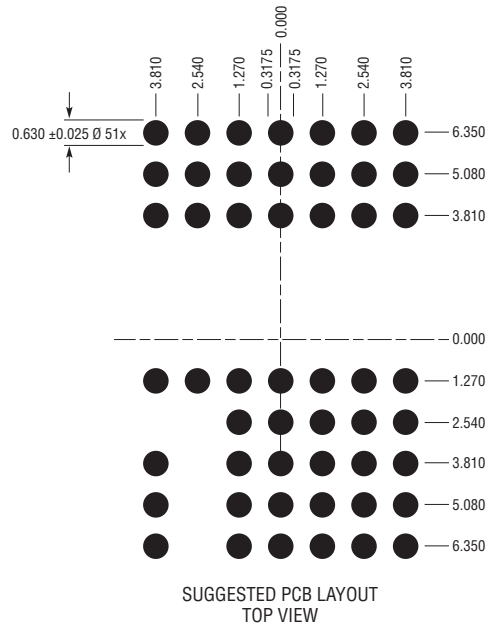
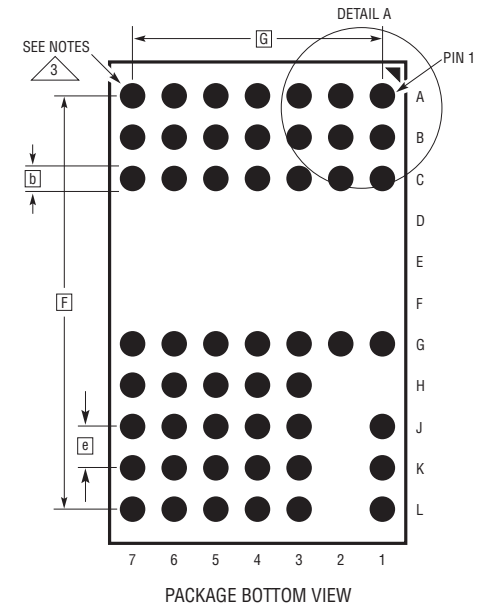
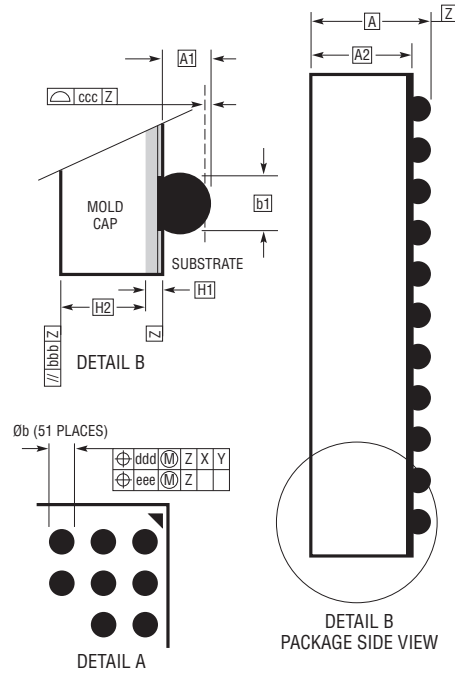
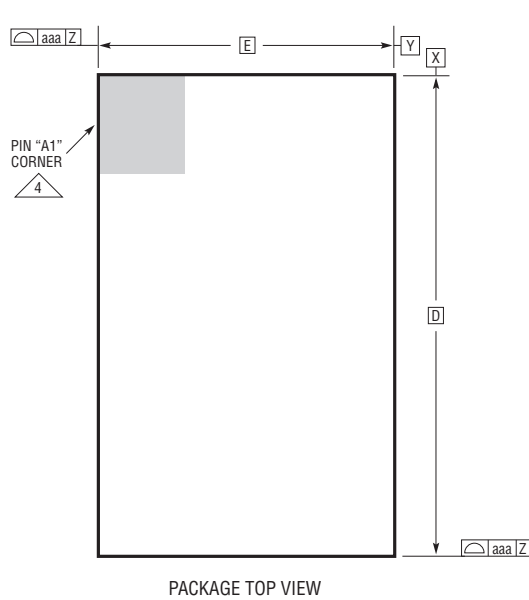


BGA Package
51-Lead (15.00mm × 9.00mm × 4.92mm)
 (Reference LTC DWG# 05-08-1889 Rev 0)



DIMENSIONS				
SYMBOL	MIN	NOM	MAX	NOTES
A	4.72	4.92	5.12	
A1	0.50	0.60	0.70	
A2	4.22	4.32	4.42	
b	0.71	0.78	0.85	
b1	0.60	0.63	0.66	
D	15.00			
E	9.00			
e	1.27			
F	12.70			
G	7.62			
H1	0.27	0.32	0.37	
H2	3.95	4.00	4.05	
aaa			0.15	
bbb			0.10	
ccc			0.20	
ddd			0.30	
eee			0.15	
TOTAL NUMBER OF BALLS: 51				

- NOTES:
- DIMENSIONING AND TOLERANCING PER ASME Y14.5M-1994
 - ALL DIMENSIONS ARE IN MILLIMETERS
 - BALL DESIGNATION PER JESD MS-028 AND JEP95
 - DETAILS OF PIN #1 IDENTIFIER ARE OPTIONAL, BUT MUST BE LOCATED WITHIN THE ZONE INDICATED. THE PIN #1 IDENTIFIER MAY BE EITHER A MOLD OR MARKED FEATURE
 - PRIMARY DATUM -Z- IS SEATING PLANE
 - SOLDER BALL COMPOSITION CAN BE 96.5% Sn/3.0% Ag/0.5% Cu OR Sn Pb EUTECTIC

